DM3 SERIES RECOMMENDED CONDITION SPECIFICATIONS FOR SOLDERING a) HAND SOLDERING: 350 ℃ 3 SECONDS b) RECOMMENDED REFLOW CONDITION (RECOMMENDED TEMPERATURE PROFILE) TEMPERATURE (* PEAK: MAX 250℃(5seconds) 250 MIN 230°C 200 (50 SECONDS) SOLDERING TIME 150℃ 90 TO 120 SECONDS PRE-HEATING TIME TIME (SECONDS) APPLICABLE CONDITIONS D: FAR-INFRARED AND II...
ATMOSPHERE
AM TYPE Sn/3.0Ag/0.5Cu
CM705-221CM5-42-10.5/PRODUCT MADE IN SENJU KINZOKU)
TF - GLASS EPOXY 60×100×1mm REFLOW METHOD: FAR-INFRARED AND HOT AIR COMBINED REFLOW REFLOW AIR : ATMOSPHERE D SOLDER: CREAM TYPE Sn/3. OAg/O.5Cu TEST SUBSTRATE: GLASS EPOXY 60×100×1mm METAL MASK THICKNESS: 0.12mm REFLOW TO BE 2 TIMES MAX. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. Ε Ε ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, MANUFACTURE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. 部番 材 質 処 理 備 考 部番 材 質 処 理 備 考 年月日 計 検 SCALE 記 △の数 UNITS FREE ᠕ m m: NH. NAKATA 20181004 図番: 認 EDC-327223-00-00 HIROSE 検 义 : HT. YAMAGUCHI 20181003 DM3-SERIES 製品名: ELECTRIC : TY. EDAGAWA 20181003 設 計 CO. LTD. 20181003 製品 CL609 図 : TY. EDAGAWA FORM HC0011-5-1 3 4